

Abstract

An improved stacked-die package includes an interposer which improves the manufacturability of the package. A semiconductor package includes a package substrate having a plurality of bond pads; a first semiconductor device mounted on the package substrate, the first semiconductor device having a plurality of bond pads provided thereon; an interposer mounted on the first semiconductor device, the interposer having a first interposer bond pad and a second interposer bond pad, wherein the first and second interposer bond pads are electrically coupled; a second semiconductor device mounted on the interposer, the second semiconductor device having a plurality of bond pads provided thereon; a first bond wire connected to one of the plurality of bond pads on said first semiconductor and to the first interposer bond pad; and a second bond wire connected to the second interposer bond pad and to one of the plurality of bond pads on the semiconductor device.

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